

**WHAT IS CLAIMED IS:**

1. A cooling structure for an electronic element, wherein the structure comprises:

an extended portion formed on an inner baffle and contacting an upper surface of a heat-producing electronic element, wherein the inner baffle and the heat-producing electronic element are mounted on an inner circuit substrate;

a plurality of through holes formed on the inner circuit substrate underneath the heat-producing electronic element;

a baffle case surrounding the inner baffle, the extended portion, the heat-producing electronic element, and the inner circuit substrate, the baffle case having an upper side and a lower side;

a radiating plate mounted on the upper side of the baffle; and

a plurality of baffle case holes through the lower side of the baffle case.

2. The structure as defined in claim 1 further comprising:

an external circuit substrate with an upper side and a lower side, wherein the upper side of the external circuit substrate further comprises a heat sink contacting the lower side of the baffle case; and

a plurality of external circuit substrate holes through external circuit substrate to correspondingly communicate with said baffle case holes of said baffle case.

3. The structure as defined in claim 2, wherein the heat sink is a flat surface made of metal formed on said external circuit substrate by a open mask soldering process.

4. The structure as defined in claim 3, wherein the metal is lead.

5. The structure as defined in claim 1, wherein the electronic element is a power

**amplifying module of a code division multiple access modem.**